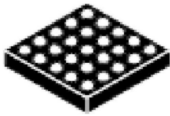
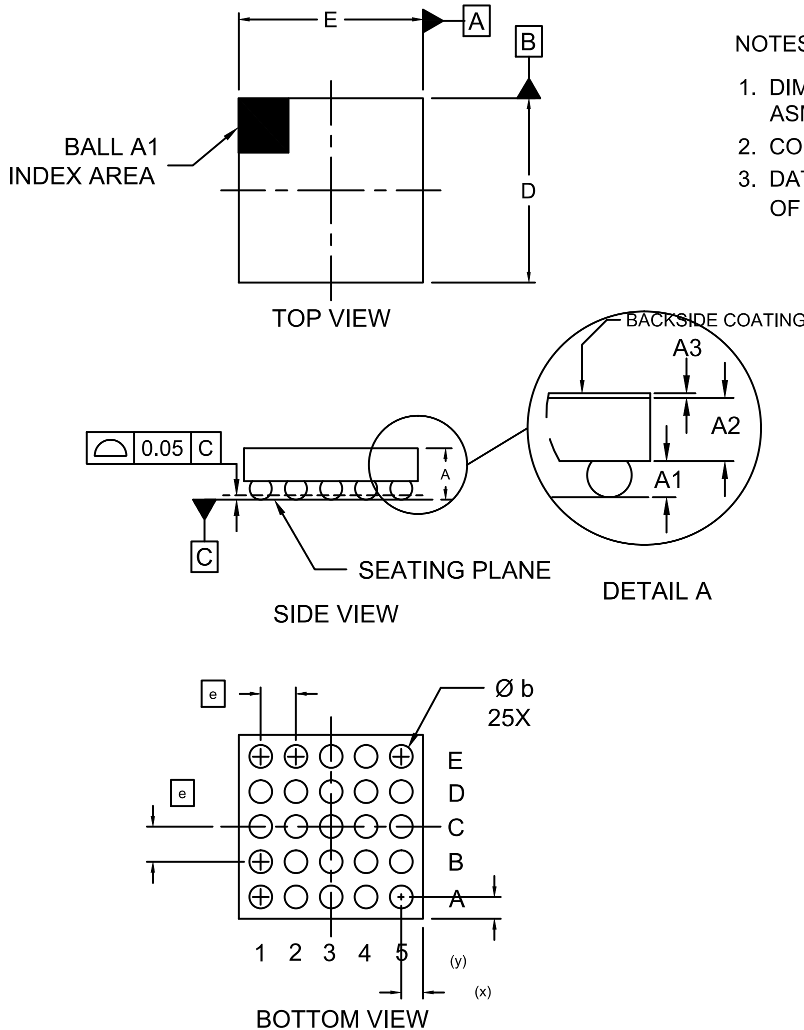


WLCSP25 2.16x2.16x0.574
CASE 567YL
ISSUE O

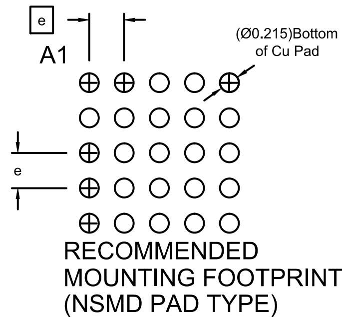
DATE 16 SEP 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.536	0.574	0.612
A1	0.176	0.196	0.216
A2	0.338	0.353	0.368
A3	0.022	0.025	0.028
b	0.24	0.26	0.28
D	2.13	2.16	2.19
E	2.13	2.16	2.19
e	0.40 BASIC		
x	0.265	0.280	0.295
y	0.265	0.280	0.295



RECOMMENDED
MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	WLCSP25 2.16x2.16x0.574	PAGE 1 OF 1

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